

### **Abstract of the Disclosure**

The present invention provides a semiconductor device comprising a die pad section (200), a first semiconductor chip (4) having a surface (41) formed with a first electrode section (47) and a back surface (42) fixed to the die pad section (200), a second semiconductor chip (5) having a surface (51) formed with a second electrode section (57) and a back surface (52) fixed to the surface (41) of the first semiconductor chip (4), a support member (300) having a surface (301) fixed to the back surface of the second semiconductor chip (5) and a back surface (302) fixed to the die pad section (200), lead terminal sections (210, 220) respectively electrically connected to the first and second electrode sections (47, 57), and a resin encapsulating body (10) that seals the die pad section (200), the first and second semiconductor chips (4, 5) and the support member (300).